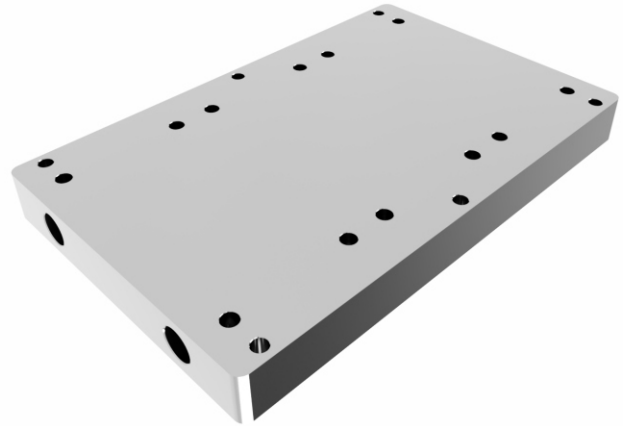


HIGH PERFORMANCE Thermal Management

Q-CHILL Internal Fin Technology

007-MXQ-01 Liquid Cooled Coldplate

The 007-MXQ-01 is a liquid cooled coldplate specifically designed for challenging power density applications requiring a compact and light-weight design. The advanced design of the 007-MXQ-01 allows for efficient heat transfer between the coldplate contact area and the power module base plate.



Applications

- Electric Vehicle Motor Drives
- Wind Turbines
- Solar Inverters
- Industrial Motor Controls
- Power Converters
- Induction Heaters
- Rail Traction Systems
- Auxilliary Vehicle Systems
- High Performance Motor Sport

Compatible Power Module Packages

This coldplate will cool any three of the following:

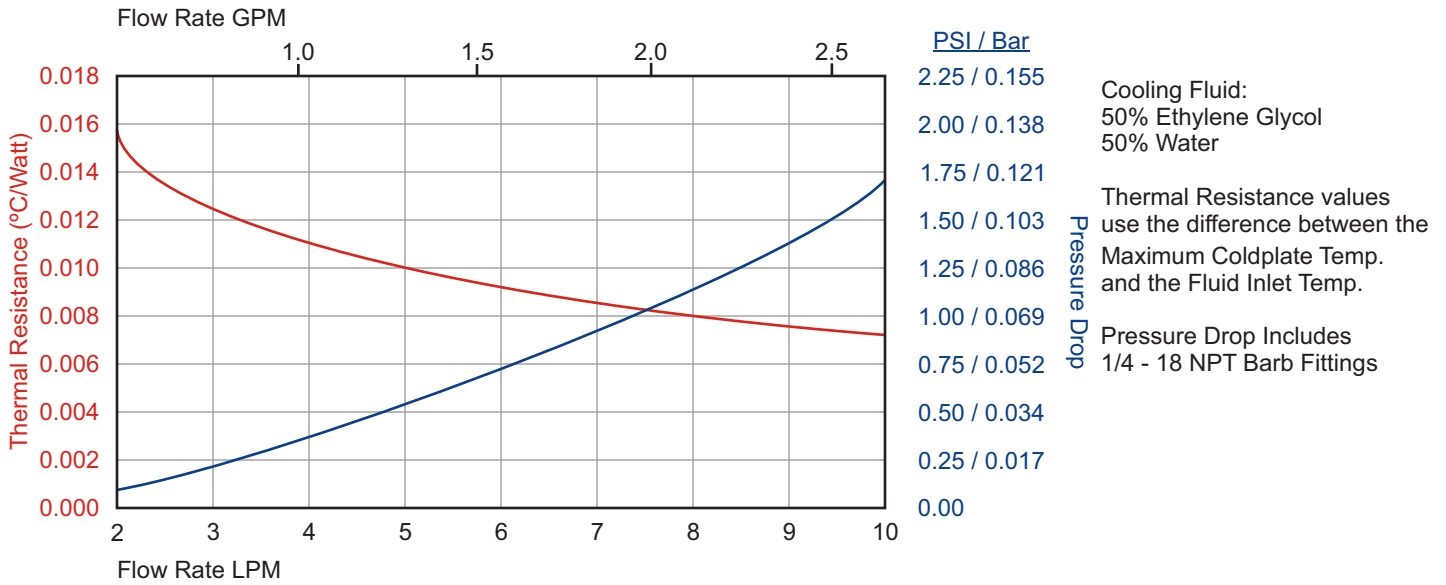
- SEMIKRON SEMiTRANS® Case D56
- INFINEON 62mm Package
- FUJI Semiconductor M127, M234, and M235
- POWEREX 62mm Package



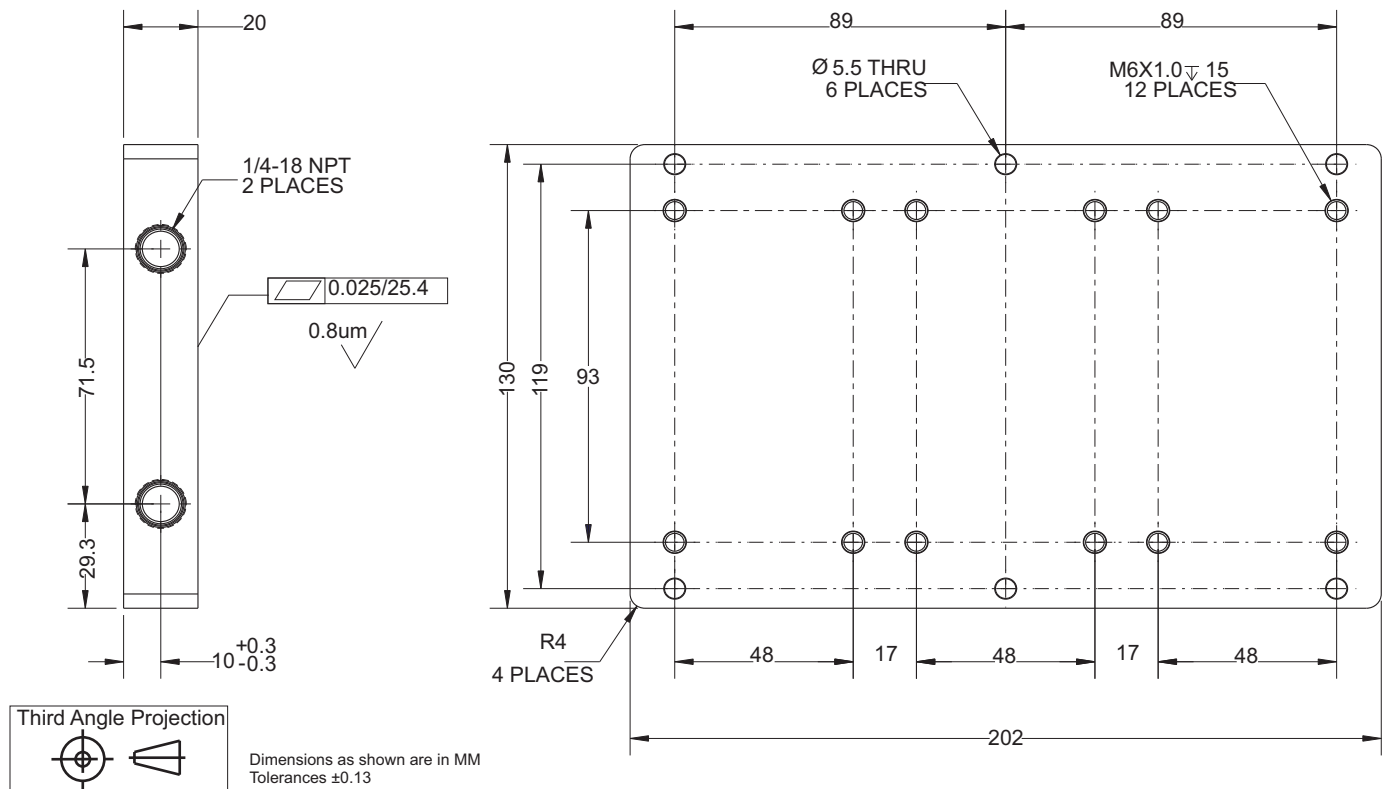
Features

- 3000 Watt heat rejection @ 8 LPM with a 24° C temperature rise from the fluid inlet to the maximum coldplate temperature
- Patent pending Q-CHILL internal fin technology provides for a more uniform top coldplate surface temperature
- Low pressure drop for reduced system cost (1.16 PSI @ 8 LPM)
- Low cost proven aluminum solution with performance comparable to copper based solutions
- Power Compact and light (1.2 kg)
- Compatible with industry accepted coolants
- Metallurgical seal for robustness and a high pressure rating

PERFORMANCE CURVES



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